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Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	12
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	FLASH
EEPROM Size	128 x 8
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	14-SOIC (0.154", 3.90mm Width)
Supplier Device Package	14-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f676-i-sl

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PIC16F630/676

TABLE 2-2: PIC16F630/676 SPECIAL FUNCTION REGISTERS SUMMARY BANK 1

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Page
Bank 1											
80h	INDF	Addressing	this location	uses content	s of FSR to a	address data	memory (not	a physical re	egister)	xxxx xxxx	20,63
81h	OPTION_REG	RAPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	14,32
82h	PCL	Program Co	unter's (PC)	Least Signifi	cant Byte	l .	l .	l .		0000 0000	19
83h	STATUS	IRP ⁽²⁾	RP1 ⁽²⁾	RP0	TO	PD	Z	DC	С	0001 1xxx	13
84h	FSR	Indirect data	a memory Ad		r					xxxx xxxx	20
85h	TRISA	_	_	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	11 1111	21
86h	_	Unimplemen	nted							_	_
87h	TRISC	_	_	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	11 1111	_
88h	_	Unimplemen	nimplemented							_	_
89h	_	Unimplemen	Jnimplemented					_	_		
8Ah	PCLATH	_	_	ı	Write buffer	for upper 5 b	oits of prograi	m counter		0 0000	19
8Bh	INTCON	GIE	PEIE	TOIE	INTE	RAIE	TOIF	INTF	RAIF	0000 0000	15
8Ch	PIE1	EEIE	ADIE	ı	_	CMIE	_	_	TMR1IE	00 00	16
8Dh	_	Unimplemer	nted							_	_
8Eh	PCON	_	_	_	_	_	_	POR	BOD	qq	18
8Fh	_									-	
90h	OSCCAL	CAL5	CAL4	CAL3	CAL2	CAL1	CAL0	_	_	1000 00	18
91h	ANSEL ⁽³⁾	ANS7	ANS6	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0	1111 1111	48
92h	_	Unimplemen	nted		•				•	_	_
93h	_	Unimplemen	nted							_	_
94h	_	Unimplemen	nted							_	_
95h	WPUA	_	_	WPUA5	WPUA4	_	WPUA2	WPUA1	WPUA0	11 -111	22
96h	IOCA	_	_	IOCA5	IOCA4	IOCA3	IOCA2	IOCA1	IOCA0	00 0000	23
97h	_	Unimplemen	nted		•				•	_	_
98h	_	Unimplemen	nted							_	_
99h	VRCON	VREN	_	VRR	_	VR3	VR2	VR1	VR0	0-0- 0000	44
9Ah	EEDAT	EEPROM da	EEPROM data register								51
9Bh	EEADR	_									51
9Ch	EECON1	_	_	_	_	WRERR	WREN	WR	RD	x000	52
9Dh	EECON2	EEPROM co	EPROM control register 2 (not a physical register)								51
9Eh	ADRESL ⁽³⁾	Least Signif	icant 2 bits o	f the left shift	ed result or 8	bits of the ri	ght shifted re	sult		xxxx xxxx	46
9Fh	ADCON1 ⁽³⁾	_	ADCS2	ADCS1	ADCS0	_	_	_	_	-000	47,63

- = Unimplemented locations read as '0', u = unchanged, x = unknown, q = value depends on condition, shaded = unimplemented Other (non Power-up) Resets include \overline{MCLR} Reset, Brown-out Detect and Watchdog Timer Reset during normal operation. IRP and RP1 bits are reserved, always maintain these bits clear. Legend:

Note 1:

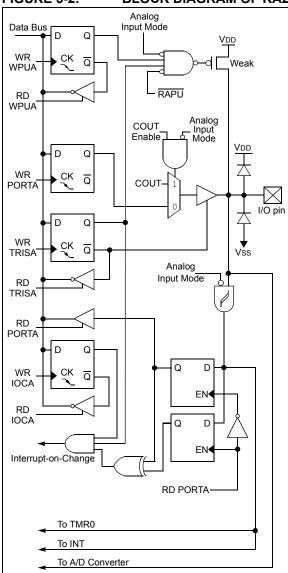
^{3:} PIC16F676 only.

3.2.3.3 RA2/AN2/T0CKI/INT/COUT

Figure 3-2 shows the diagram for this pin. The RA2 pin is configurable to function as one of the following:

- · a general purpose I/O
- an analog input for the A/D (PIC16F676 only)
- · a digital output from the comparator
- · the clock input for TMR0
- · an external edge triggered interrupt

FIGURE 3-2: BLOCK DIAGRAM OF RA2

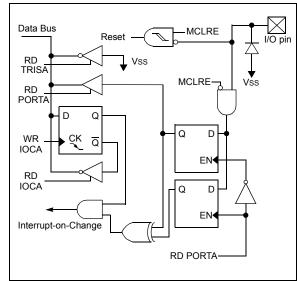


3.2.3.4 RA3/MCLR/VPP

Figure 3-3 shows the diagram for this pin. The RA3 pin is configurable to function as one of the following:

- · a general purpose input
- · as Master Clear Reset

FIGURE 3-3: BLOCK DIAGRAM OF RA3



REGISTER 3-5: PORTC — PORTC REGISTER (ADDRESS: 07h)

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
_	_	RC5	RC4	RC3	RC2	RC1	RC0
bit 7							bit 0

bit 7-6: **Unimplemented**: Read as '0'

bit 5-0: **PORTC<5:0>**: General Purpose I/O pin bits

1 = Port pin is >VIH 0 = Port pin is <VIL

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
- n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

REGISTER 3-6: TRISC — PORTC TRI-STATE REGISTER (ADDRESS: 87h)

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
_	_	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0
bit 7							bit 0

bit 7-6: **Unimplemented**: Read as '0'

bit 5-0: TRISC<5:0>: PORTC Tri-State Control bits

1 = PORTC pin configured as an input (tri-stated)

0 = PORTC pin configured as an output

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
- n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

TABLE 3-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTC

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Value on all other Resets
07h	PORTC	_	_	RC5	RC4	RC3	RC2	RC1	RC0	xx xxxx	uu uuuu
87h	TRISC	_	_	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	11 1111	11 1111
91h	ANSEL ⁽¹⁾	ANS7	ANS6	ANS5	ANS4	ANS3	ANS2	ANS1	ANS0	1111 1111	1111 1111

Note 1: PIC16F676 only.

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTC.

5.1 Timer1 Modes of Operation

Timer1 can operate in one of three modes:

- · 16-bit timer with prescaler
- 16-bit synchronous counter
- · 16-bit asynchronous counter

In Timer mode, Timer1 is incremented on every instruction cycle. In Counter mode, Timer1 is incremented on the rising edge of the external clock input T1CKI. In addition, the Counter mode clock can be synchronized to the microcontroller system clock or run asynchronously.

In counter and timer modules, the counter/timer clock can be gated by the $\overline{\text{T1G}}$ input.

If an external clock oscillator is needed (and the microcontroller is using the INTOSC w/o CLKOUT), Timer1 can use the LP oscillator as a clock source.

Note: In Counter mode, a falling edge must be registered by the counter prior to the first incrementing rising edge.

5.2 Timer1 Interrupt

The Timer1 register pair (TMR1H:TMR1L) increments to FFFFh and rolls over to 0000h. When Timer1 rolls over, the Timer1 interrupt flag bit (PIR1<0>) is set. To enable the interrupt on rollover, you must set these bits:

- Timer1 interrupt Enable bit (PIE1<0>)
- PEIE bit (INTCON<6>)
- GIE bit (INTCON<7>).

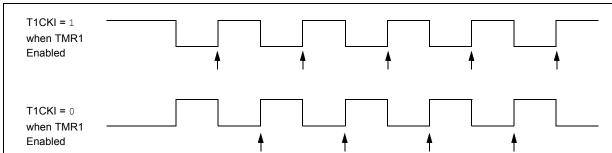
The interrupt is cleared by clearing the TMR1IF in the Interrupt Service Routine.

Note: The TMR1H:TTMR1L register pair and the TMR1IF bit should be cleared before enabling interrupts.

5.3 Timer1 Prescaler

Timer1 has four prescaler options allowing 1, 2, 4, or 8 divisions of the clock input. The T1CKPS bits (T1CON<5:4>) control the prescale counter. The prescale counter is not directly readable or writable; however, the prescaler counter is cleared upon a write to TMR1H or TMR1L.

FIGURE 5-2: TIMER1 INCREMENTING EDGE



- Note 1: Arrows indicate counter increments.
 - 2: In Counter mode, a falling edge must be registered by the counter prior to the first incrementing rising edge of the clock.

REGISTER 6-2: VRCON — VOLTAGE REFERENCE CONTROL REGISTER (ADDRESS: 99h)

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
VREN	_	VRR	_	VR3	VR2	VR1	VR0
bit 7							bit 0

bit 7 VREN: CVREF Enable bit

1 = CVREF circuit powered on

0 = CVREF circuit powered down, no IDD drain

bit 6 **Unimplemented:** Read as '0'

bit 5 VRR: CVREF Range Selection bit

1 = Low range0 = High range

bit 4 Unimplemented: Read as '0'

bit 3-0 **VR3:VR0:** CVREF value selection bits $0 \le VR$ [3:0] ≤ 15

When VRR = 1: CVREF = (VR3:VR0 / 24) * VDD

When VRR = 0: CVREF = VDD/4 + (VR3:VR0 / 32) * VDD

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

- n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

6.9 Comparator Interrupts

The comparator interrupt flag is set whenever there is a change in the output value of the comparator. Software will need to maintain information about the status of the output bits, as read from CMCON<6>, to determine the actual change that has occurred. The CMIF bit, PIR1<3>, is the comparator interrupt flag. This bit must be reset in software by clearing it to '0'. Since it is also possible to write a '1' to this register, a simulated interrupt may be initiated.

The CMIE bit (PIE1<3>) and the PEIE bit (INTCON<6>) must be set to enable the interrupt. In addition, the GIE bit must also be set. If any of these bits are cleared, the interrupt is not enabled, though the CMIF bit will still be set if an interrupt condition occurs.

The user, in the Interrupt Service Routine, can clear the interrupt in the following manner:

- a) Any read or write of CMCON. This will end the mismatch condition.
- b) Clear flag bit CMIF.

A mismatch condition will continue to set flag bit CMIF. Reading CMCON will end the mismatch condition and allow flag bit CMIF to be cleared.

Note: If a change in the CMCON register (COUT) should occur when a read operation is being executed (start of the Q2 cycle), then the CMIF (PIR1<3>) interrupt flag may not get set.

TABLE 6-2: REGISTERS ASSOCIATED WITH COMPARATOR MODULE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Value on all other Resets
0Bh/8Bh	INTCON	GIE	PEIE	TOIE	INTE	RAIE	TOIF	INTF	RAIF	0000 0000	0000 000u
0Ch	PIR1	EEIF	ADIF	_	_	CMIF	_	_	TMR1IF	00 00	00 00
19h	CMCON	_	COUT	_	CINV	CIS	CM2	CM1	CM0	-0-0 0000	-0-0 0000
8Ch	PIE1	EEIE	ADIE	_	_	CMIE	_	_	TMR1IE	00 00	00 00
85h	TRISA	_	_	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	11 1111	11 1111
99h	VRCON	VREN	_	VRR	_	VR3	VR2	VR1	VR0	0-0- 0000	0-0- 0000

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by the comparator module.

7.2 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 7-3. The source impedance (Rs) and the internal sampling switch (Rss) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (Rss) impedance varies over the device voltage (VDD), see Figure 7-3. The maximum recommended impedance for analog sources is $10~\mathrm{k}\Omega$. As the impedance

is decreased, the acquisition time may be decreased. After the analog input channel is selected (changed), this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, Equation 7-1 may be used. This equation assumes that 1/2 LSb error is used (1024 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified resolution.

To calculate the minimum acquisition time, TACQ, see the PIC[®] Mid-Range Reference Manual (DS33023).

EQUATION 7-1: ACQUISITION TIME

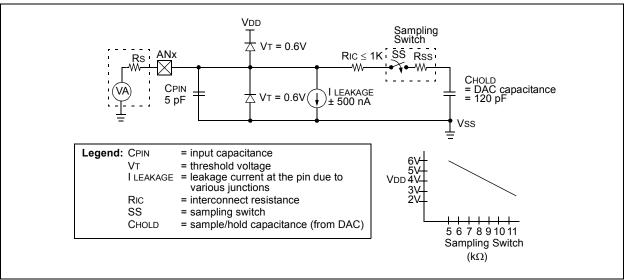
TACQ = Amplifier Settling Time +
Hold Capacitor Charging Time +
Temperature Coefficient

= TAMP + TC + TCOFF
= $2\mu s + TC + [(Temperature -25^{\circ}C)(0.05\mu s/^{\circ}C)]$ TC = CHOLD (RIC + RSs + Rs) In(1/2047)
= $-120pF (1k\Omega + 7k\Omega + 10k\Omega) In(0.0004885)$ = $16.47\mu s$ TACQ = $2\mu s + 16.47\mu s + [(50^{\circ}C -25^{\circ}C)(0.05\mu s/^{\circ}C)]$ = $19.72\mu s$

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

- 2: The charge holding capacitor (CHOLD) is not discharged after each conversion.
- 3: The maximum recommended impedance for analog sources is 10 k Ω . This is required to meet the pin leakage specification.

FIGURE 7-3: ANALOG INPUT MODEL



8.0 DATA EEPROM MEMORY

The EEPROM data memory is readable and writable during normal operation (full VDD range). This memory is not directly mapped in the register file space. Instead, it is indirectly addressed through the Special Function Registers. There are four SFRs used to read and write this memory:

- EECON1
- EECON2 (not a physically implemented register)
- EEDATA
- EEADR

EEDATA holds the 8-bit data for read/write, and EEADR holds the address of the EEPROM location being accessed. PIC16F630/676 devices have 128 bytes of data EEPROM with an address range from 0h to 7Fh.

The EEPROM data memory allows byte read and write. A byte write automatically erases the location and writes the new data (erase before write). The EEPROM data memory is rated for high erase/write cycles. The write time is controlled by an on-chip timer. The write time will vary with voltage and temperature as well as from chip to chip. Please refer to AC Specifications for exact limits.

When the data memory is code-protected, the CPU may continue to read and write the data EEPROM memory. The device programmer can no longer access this memory.

Additional information on the data EEPROM is available in the $PIC^{\$}$ Mid-Range Reference Manual, (DS33023).

REGISTER 8-1: EEDAT — EEPROM DATA REGISTER (ADDRESS: 9Ah)

| R/W-0 |
|--------|--------|--------|--------|--------|--------|--------|--------|
| EEDAT7 | EEDAT6 | EEDAT5 | EEDAT4 | EEDAT3 | EEDAT2 | EEDAT1 | EEDAT0 |
| bit 7 | | | | | | | bit 0 |

bit 7-0 **EEDATn**: Byte value to write to or read from data EEPROM

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented	bit, read as '0'
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

REGISTER 8-2: EEADR — EEPROM ADDRESS REGISTER (ADDRESS: 9Bh)

U-0	R/W-0						
_	EADR6	EADR5	EADR4	EADR3	EADR2	EADR1	EADR0
bit 7							bit 0

bit 7 **Unimplemented**: Should be set to '0'

bit 6-0 **EEADR**: Specifies one of 128 locations for EEPROM Read/Write Operation

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented	bit, read as '0'
- n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

8.1 EEADR

The EEADR register can address up to a maximum of 128 bytes of data EEPROM. Only seven of the eight bits in the register (EEADR<6:0>) are required. The MSb (bit 7) is ignored.

The upper bit should always be '0' to remain upward compatible with devices that have more data EEPROM memory.

8.2 EECON1 AND EECON2 REGISTERS

EECON1 is the control register with four low order bits physically implemented. The upper four bits are non-implemented and read as '0's.

Control bits RD and WR initiate read and write, respectively. These bits cannot be cleared, only set, in software. They are cleared in hardware at completion

of the read or write operation. The inability to clear the WR bit in software prevents the accidental, premature termination of a write operation.

The WREN bit, when set, will allow a write operation. On power-up, the WREN bit is clear. The WRERR bit is set when a write operation is interrupted by a MCLR Reset, or a WDT Time-out Reset during normal operation. In these situations, following Reset, the user can check the WRERR bit, clear it, and rewrite the location. The data and address will be cleared, therefore, the EEDATA and EEADR registers will need to be re-initialized.

The Interrupt flag bit EEIF in the PIR1 register is set when the write is complete. This bit must be cleared in software.

EECON2 is not a physical register. Reading EECON2 will read all '0's. The EECON2 register is used exclusively in the data EEPROM write sequence.

REGISTER 8-3: EECON1 — EEPROM CONTROL REGISTER (ADDRESS: 9Ch)

U-0	U-0	U-0	U-0	R/W-x	R/W-0	R/S-0	R/S-0
_	_	_	_	WRERR	WREN	WR	RD
bit 7							bit 0

bit 7-4 Unimplemented: Read as '0'

bit 3 WRERR: EEPROM Error Flag bit

- 1 = A write operation is prematurely terminated (any MCLR Reset, any WDT Reset during normal operation or BOD detect)
- 0 = The write operation completed

bit 2 WREN: EEPROM Write Enable bit

- 1 = Allows write cycles
- 0 = Inhibits write to the data EEPROM

bit 1 WR: Write Control bit

- 1 = Initiates a write cycle (The bit is cleared by hardware once write is complete. The WR bit can only be set, not cleared, in software.)
- 0 = Write cycle to the data EEPROM is complete

bit 0 RD: Read Control bit

- 1 = Initiates an EEPROM read (Read takes one cycle. RD is cleared in hardware. The RD bit can only be set, not cleared, in software.)
- 0 = Does not initiate an EEPROM read

Legend:

S = Bit can only be set

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

- n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

TABLE 9-3: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Powe	er-up	Brown-o	ut Detect	Wake-up
Oscillator Corniguration	PWRTE = 0	PWRTE = 1	PWRTE = 0	PWRTE = 1	from Sleep
XT, HS, LP	TPWRT + 1024•Tosc	1024•Tosc	TPWRT + 1024•Tosc	1024•Tosc	1024•Tosc
RC, EC, INTOSC	TPWRT	_	TPWRT	_	_

TABLE 9-4: STATUS/PCON BITS AND THEIR SIGNIFICANCE

POR	BOD	TO	PD	
0	u	1	1	Power-on Reset
1	0	1	1	Brown-out Detect
u	u	0	u	WDT Reset
u	u	0	0	WDT Wake-up
u	u	u	u	MCLR Reset during normal operation
u	u	1	0	MCLR Reset during Sleep

Legend: u = unchanged, x = unknown

TABLE 9-5: SUMMARY OF REGISTERS ASSOCIATED WITH BROWN-OUT

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOD	Value on all other Resets ⁽¹⁾
03h	STATUS	IRP	RP1	RPO	TO	PD	Z	DC	С	0001 1xxx	000q quuu
8Eh	PCON	_		_	_	_	_	POR	BOD	0x	uq

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0', <math>q = value depends on condition.

Note 1: Other (non Power-up) Resets include MCLR Reset, Brown-out Detect and Watchdog Timer Reset during normal operation.

TABLE 9-6: INITIALIZATION CONDITION FOR SPECIAL REGISTERS

Condition	Program Counter	STATUS Register	PCON Register						
Power-on Reset	000h	0001 1xxx	0x						
MCLR Reset during normal operation	000h	000u uuuu	uu						
MCLR Reset during Sleep	000h	0001 Ouuu	uu						
WDT Reset	000h	0000 uuuu	uu						
WDT Wake-up	PC + 1	uuu0 0uuu	uu						
Brown-out Detect	000h	0001 1uuu	10						
Interrupt Wake-up from Sleep	PC + 1 ⁽¹⁾	uuu1 0uuu	uu						

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0'.

Note 1: When the wake-up is due to an interrupt and global enable bit GIE is set, the PC is loaded with the interrupt vector (0004h) after execution of PC + 1.

PIC16F630/676

NOTES:

12.0 ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings†

Ambient temperature under bias	40 to +125°C
Storage temperature	65°C to +150°C
Voltage on VDD with respect to Vss	0.3 to +6.5V
Voltage on MCLR with respect to Vss	0.3 to +13.5V
Voltage on all other pins with respect to Vss	0.3V to (VDD + 0.3V)
Total power dissipation ⁽¹⁾	800 mW
Maximum current out of Vss pin	300 mA
Maximum current into VDD pin	250 mA
Input clamp current, Iik (VI < 0 or VI > VDD)	± 20 mA
Output clamp current, lok (Vo < 0 or Vo >VDD)	± 20 mA
Maximum output current sunk by any I/O pin	25 mA
Maximum output current sourced by any I/O pin	25 mA
Maximum current sunk by PORTA and PORTC (combined)	200 mA
Maximum current sourced PORTA and PORTC (combined)	200 mA

Note 1: Power dissipation is calculated as follows: PDIS = VDD x {IDD - \sum IOH} + \sum {(VDD-VOH) x IOH} + \sum (VOI x IOL).

† NOTICE: Stresses above those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

Note: Voltage spikes below Vss at the $\overline{\text{MCLR}}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100 Ω should be used when applying a "low" level to the $\overline{\text{MCLR}}$ pin, rather than pulling this pin directly to Vss.

12.4 DC Characteristics: PIC16F630/676-E (Extended)

	Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \le \text{TA} \le +125^{\circ}\text{C}$ for extended							
Param	Device Characteristics	Min	Tunt	Max	Units		Conditions	
No.	Device Characteristics	IVIIII	Typ†	IVIAX	Ullis	V DD	Note	
D010E	Supply Current (IDD)	_	9	16	μΑ	2.0	Fosc = 32 kHz	
		_	18	28	μΑ	3.0	LP Oscillator Mode	
		_	35	54	μΑ	5.0		
D011E		_	110	150	μΑ	2.0	Fosc = 1 MHz	
		_	190	280	μΑ	3.0	XT Oscillator Mode	
		_	330	450	μΑ	5.0		
D012E		_	220	280	μΑ	2.0	Fosc = 4 MHz	
		_	370	650	μΑ	3.0	XT Oscillator Mode	
		_	0.6	1.4	mA	5.0		
D013E		_	70	110	μΑ	2.0	Fosc = 1 MHz	
		_	140	250	μΑ	3.0	EC Oscillator Mode	
		_	260	390	μΑ	5.0		
D014E		_	180	250	μΑ	2.0	Fosc = 4 MHz	
		_	320	470	μΑ	3.0	EC Oscillator Mode	
		_	580	850	μΑ	5.0		
D015E			340	450	μΑ	2.0	Fosc = 4 MHz	
		_	500	780	μΑ	3.0	INTOSC Mode	
		<u> </u>	8.0	1.1	mA	5.0		
D016E			180	250	μΑ	2.0	Fosc = 4 MHz	
		_	320	450	μΑ	3.0	EXTRC Mode	
		_	580	800	μΑ	5.0		
D017E			2.1	2.95	mA	4.5	Fosc = 20 MHz	
			2.4	3.0	mA	5.0	HS Oscillator Mode	

[†] Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all IDD measurements in Active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD; MCLR = VDD; WDT disabled.

^{2:} The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

12.6 DC Characteristics: PIC16F630/676-I (Industrial), PIC16F630/676-E (Extended)

DC CHA	ARACT	TERISTICS	Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \le \text{TA} \le +85^{\circ}\text{C}$ for industrial $-40^{\circ}\text{C} \le \text{TA} \le +125^{\circ}\text{C}$ for extended				5°C for industrial
Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
		Input Low Voltage					
	VIL	I/O ports					
D030		with TTL buffer	Vss	_	8.0	V	$4.5V \le VDD \le 5.5V$
D030A			Vss	_	0.15 VDD	V	Otherwise
D031		with Schmitt Trigger buffer	Vss	_	0.2 VDD	V	Entire range
D032		MCLR, OSC1 (RC mode)	Vss	_	0.2 VDD	V	
D033		OSC1 (XT and LP modes)	Vss	_	0.3	V	(Note 1)
D033A		OSC1 (HS mode)	Vss	_	0.3 VDD	V	(Note 1)
		Input High Voltage					
	VIH	I/O ports		_			
D040		with TTL buffer	2.0	_	Vdd	V	$4.5V \le VDD \le 5.5V$
D040A			(0.25 VDD+0.8)	_	VDD	V	otherwise
D041		with Schmitt Trigger buffer	0.8 VDD	_	VDD		entire range
D042		MCLR	0.8 VDD	_	Vdd	V	
D043		OSC1 (XT and LP modes)	1.6	_	Vdd	V	(Note 1)
D043A		OSC1 (HS mode)	0.7 VDD	_	VDD	V	(Note 1)
D043B		OSC1 (RC mode)	0.9 Vdd	_	VDD	V	
D070	IPUR	PORTA Weak Pull-up Current	50*	250	400*	μΑ	VDD = 5.0V, VPIN = VSS
		Input Leakage Current ⁽³⁾					
D060	lı∟	I/O ports	_	± 0.1	± 1	μА	Vss ≤ VPIN ≤ VDD, Pin at high-impedance
D060A		Analog inputs	_	±0.1	± 1	μΑ	$Vss \le Vpin \le Vdd$
D060B		VREF	_	± 0.1	± 1	μΑ	Vss ≤ Vpin ≤ Vdd
D061		MCLR ⁽²⁾	_	± 0.1	± 5	μΑ	$Vss \le Vpin \le Vdd$
D063		OSC1	_	± 0.1	± 5	μА	Vss ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
		Output Low Voltage					
D080	Vol	I/O ports	_	_	0.6	V	IOL = 8.5 mA, VDD = 4.5V (Ind.)
D083		OSC2/CLKOUT (RC mode)	_	_	0.6	V	IOL = 1.6 mA, VDD = 4.5V (Ind.) IOL = 1.2 mA, VDD = 4.5V (Ext.)
		Output High Voltage					
D090	Vон	I/O ports	VDD - 0.7	_	_	V	IOH = -3.0 mA, VDD = 4.5V (Ind.)
D092		OSC2/CLKOUT (RC mode)	VDD - 0.7	_	_	V	IOH = -1.3 mA, VDD = 4.5V (Ind.) IOH = -1.0 mA, VDD = 4.5V (Ext.)

^{*} These parameters are characterized but not tested.

[†] Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended to use an external clock in RC mode.

^{2:} The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

^{3:} Negative current is defined as current sourced by the pin.

TABLE 12-6: COMPARATOR SPECIFICATIONS

Comparat	or Specifications	Standard Operating Conditions -40°C to +125°C (unless otherwise stated)					
Sym Characteristics		Min	Тур	Max	Units	Comments	
Vos	Input Offset Voltage	_	± 5.0	± 10	mV		
Vсм	Input Common Mode Voltage	0	_	VDD - 1.5	V		
CMRR	Common Mode Rejection Ratio	+55*	_	_	db		
TRT	Response Time ⁽¹⁾	_	150	400*	ns		
TMC2COV Comparator Mode Change to Output Valid		_	_	10*	μS		

^{*} These parameters are characterized but not tested.

Note 1: Response time measured with one comparator input at (VDD - 1.5)/2 while the other input transitions from Vss to VDD - 1.5V.

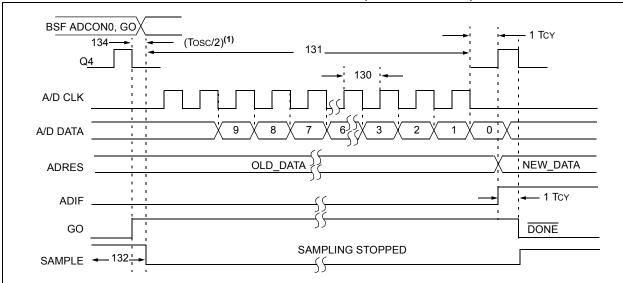
TABLE 12-7: COMPARATOR VOLTAGE REFERENCE SPECIFICATIONS

Voltage I	Reference Specifications	Standard Operating Conditions -40°C to +125°C (unless otherwise stated)					
Sym	Characteristics	Min	Тур	Max	Units	Comments	
	Resolution	_	VDD/24* VDD/32		LSb LSb	Low Range (VRR = 1) High Range (VRR = 0)	
	Absolute Accuracy Unit Resistor Value (R)		_	± 1/2* ± 1/2*	LSb LSb	Low Range (VRR = 1) High Range (VRR = 0)	
			2k*	_	Ω		
	Settling Time ⁽¹⁾	_	_	10*	μS		

^{*} These parameters are characterized but not tested.

Note 1: Settling time measured while VRR = 1 and VR<3:0> transitions from 0000 to 1111.

FIGURE 12-10: PIC16F676 A/D CONVERSION TIMING (NORMAL MODE)



Note 1: If the A/D clock source is selected as RC, a time of Tcy is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

TABLE 12-9: PIC16F676 A/D CONVERSION REQUIREMENTS

Param No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
130	TAD	A/D Clock Period	1.6	_	_	μS	Tosc based, VREF ≥ 3.0V
			3.0*	_	_	μS	Tosc based, VREF full range
130	TAD	A/D Internal RC Oscillator Period	3.0*	6.0	9.0*	μS	ADCS<1:0> = 11 (RC mode) At VDD = 2.5V
			2.0*	4.0	6.0*	μS	At VDD = 5.0V
131	TCNV	Conversion Time (not including Acquisition Time) ⁽¹⁾	_	11	_	TAD	Set GO bit to new data in A/D result register
132	TACQ	Acquisition Time	(Note 2)	11.5	_	μS	
			5*	_	_	μ\$	The minimum time is the amplifier settling time. This may be used if the "new" input voltage has not changed by more than 1 LSb (i.e., 4.1 mV @ 4.096V) from the last sampled voltage (as stored on CHOLD).
134	Tgo	Q4 to A/D Clock Start	_	Tosc/2	_	_	If the A/D clock source is selected as RC, a time of TcY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

^{*} These parameters are characterized but not tested.

Note 1: ADRES register may be read on the following TcY cycle.

2: See Table 7-1 for minimum conditions.

[†] Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

13.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES

The graphs and tables provided in this section are for design guidance and are not tested.

In some graphs or tables, the data presented are **outside specified operating range** (i.e., outside specified VDD range). This is for **information only** and devices are ensured to operate properly only within the specified range.

The data presented in this section is a **statistical summary** of data collected on units from different lots over a period of time and matrix samples. "Typical" represents the mean of the distribution at 25°C. "Max" or "min" represents (mean + 3σ) or (mean - 3σ) respectively, where σ is standard deviation, over the whole temperature range.

FIGURE 13-1: TYPICAL IPD vs. VDD OVER TEMP (-40°C TO +25°C) Typical Baseline IPD 6.0E-09 5.0E-09 4.0E-09 --40 IPD (A) 3.0E-09 0 25 2.0E-09 1.0E-09 0.0E+00 3.5 2 2.5 3 4.5 5 5.5 VDD (V)



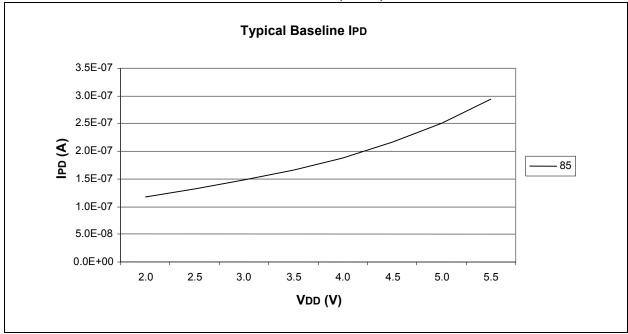


FIGURE 13-11: TYPICAL IPD WITH A/D ENABLED vs. VDD OVER TEMP (+125°C)

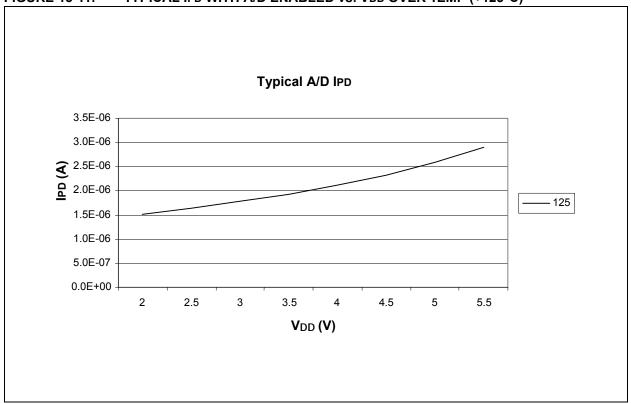
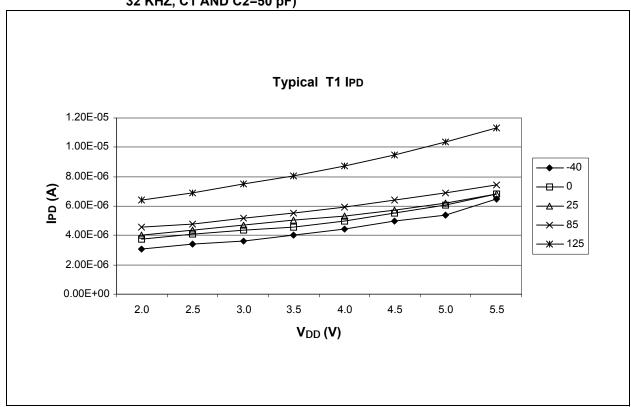
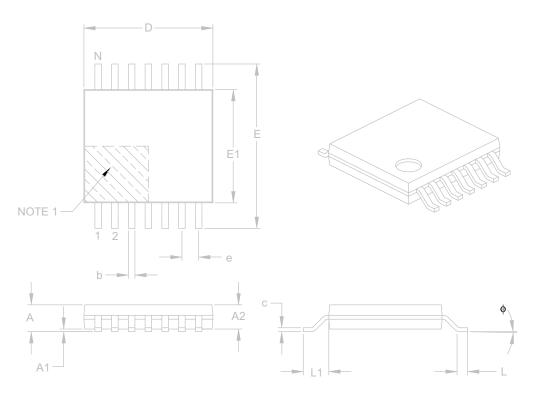


FIGURE 13-12: TYPICAL IPD WITH T1 OSC ENABLED vs. VDD OVER TEMP (-40°C TO +125°C), 32 KHZ, C1 AND C2=50 pF)



14-Lead Plastic Thin Shrink Small Outline (ST) – 4.4 mm Body [TSSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS			
Dime	nsion Limits	MIN	NOM	MAX	
Number of Pins	N	14			
Pitch	е		0.65 BSC		
Overall Height	А	-	_	1.20	
Molded Package Thickness	A2	0.80	1.00	1.05	
Standoff	A1	0.05	_	0.15	
Overall Width	E	6.40 BSC			
Molded Package Width	E1	4.30	4.40	4.50	
Molded Package Length	D	4.90	5.00	5.10	
Foot Length	L	0.45	0.60	0.75	
Footprint	L1		1.00 REF		
Foot Angle	ф	0°	_	8°	
Lead Thickness	С	0.09	_	0.20	
Lead Width	b	0.19	_	0.30	

Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
- 3. Dimensioning and tolerancing per ASME Y14.5M.
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-087B

PIC16F630/676

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